

Application No.: 10/034,030

Docket No.: JCLA8482

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of :	)	
	)	
HORNG ET AL.	)	Examiner : TRINH, MINH N
	)	
Serial No. : 10/034,030	)	Art Unit : 3729
	)	
Filed : 12/19/2001	)	Docket No. : JCLA8482
	)	
For : METHOD OF FABRICATING	)	
A CERAMIC SUBSTRATE WITH	)	
A THERMAL CONDUCTIVE PLUG	)	
OF A MULTI-CHIP PACKAGE	)	

No fee is believed to be due. However, the Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No. 50-0710 (Order No. JCLA8482).

AMENDMENT AFTER FINAL

Mail Stop AF  
Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

The Office Action mailed 04/02/2004 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.